

## N-Channel 30-V (D-S) MOSFET

### FEATURES

- Low  $R_{DS(on)}$  Provides Higher Efficiency and Extends Battery Life
- Low thermal impedance copper leadframe SOT23 saves board space
- Lower gate charge
- Fast switching speed
- High performance trench technology

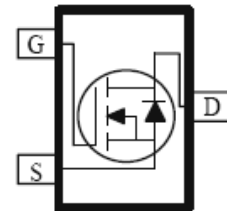
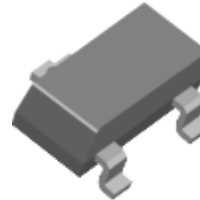
### Product Summary

MOSFET		
$V_{DS}(V)$	$R_{DS(on)} (m\Omega)$	$I_D (A)$
30 V	41 @ $V_{GS} = 10 V$	5.8
	45 @ $V_{GS} = 4.5 V$	5.0

### Description

These miniature surface mount MOSFETs utilize High Cell Density process. Low  $R_{DS(on)}$  assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are DC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

### SOT23



### Maximum Ratings (TA = 25 °C UNLESS OTHERWISE NOTED)

Symbol	Parameter	Maximum	Unit	
$V_{DS}$	Drain-Source Voltage	30	V	
$V_{GS}$	Gate-Source Voltage	$\pm 12$		
$I_D$	Continuous Drain Current <sup>a</sup>	$T_A=25^\circ C$	5.8	A
		$T_A=70^\circ C$	4.9	
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	30		
$I_S$	Continuous Source Current (Body Diode) <sup>a</sup>	2.5	A	
$P_D$	Power Dissipation <sup>a</sup>	$T_A=25^\circ C$	350	mW
$R_{\theta JA}$	Maximum Junction-to-Ambient <sup>a</sup>	357	$^\circ C/W$	
$T_J, T_{stg}$	Operation Junction and Storage Temperature Range	-55 to 150	$^\circ C$	

#### Notes:

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

**Electrical Characteristics**

SPECIFICATIONS (TA = 25°C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Limits			Unit
			Min	Typ	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.7		1.4	V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 12V$			$\pm 100$	nA
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 24V, V_{GS} = 0V$ $T_J = 25^\circ C$			1	uA
		$V_{DS} = 24V, V_{GS} = 0V,$ $T_J = 55^\circ C$			5	
Drain-Source On-Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5.8A$			41	mΩ
		$V_{GS} = 4.5V, I_D = 5.0A$			45	
		$V_{GS} = 2.5V, I_D = 4.0A$			59	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 5A$		15		S
Diode Forward On Voltage	$V_{SD}$	$I_S = 1.0A, V_{GS} = 0V$			1.0	V
Reverse Recovery Time	$T_{rr}$	$I_S = 5A, V_{GS} = 0V,$ $di/dt = 100A/\mu S$		16		nS
Reverse Recovery Charge	$Q_{rr}$			8.9		nC
<b>Dynamic <sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 15V, V_{GS} = 4.5V$ $I_D = 5.8A$		9.7	12	nC
Gate-Source Charge	$Q_{gs}$			1.6		
Gate-Drain Charge	$Q_{gd}$			3.1		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = 15V, R_L = 2.7\Omega, R_G = 3\Omega,$ $V_{GS} = 10V$		3.3		nS
Turn-On Rise Time	$t_r$			4.8		
Turn-Off Delay Time	$t_{d(off)}$			26.3		
Turn-Off Fall Time	$t_f$			4.1		
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = -15V, f = 1.0MHz$		823	1030	pF
Output Capacitance	$C_{oss}$			99		
Reverse Transfer Capacitance	$C_{rss}$			77		
Gate Resistance	$R_g$	$f = 1.0MHz$		1.2	3.6	Ω

**Notes:**

- (a) Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$   
 (b) Guaranteed by design; not subject to production testing



### Typical Electrical Characteristics (N-Channel)

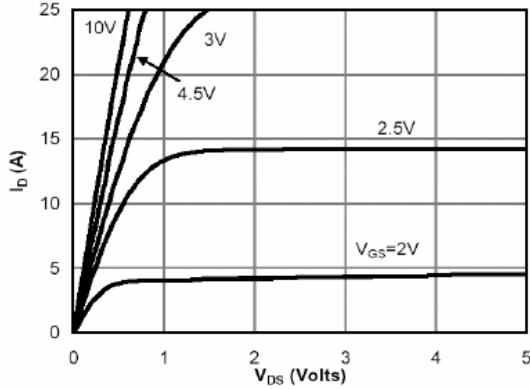


Fig 1. Typical Output Characteristics

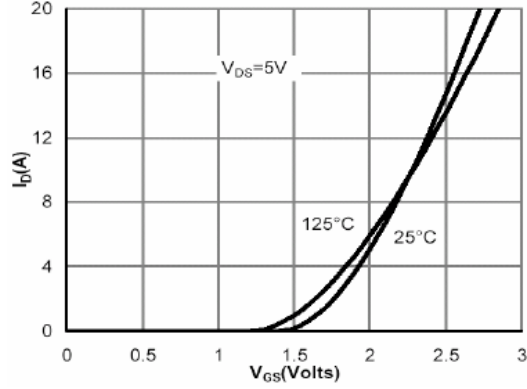


Fig 2. Transfer Characteristics

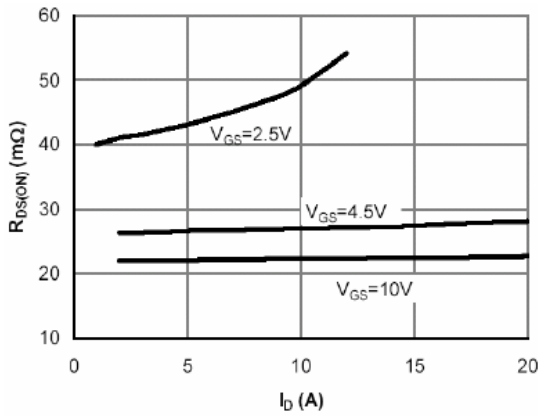


Fig 3. On-Resistance v.s. Drain Current and Gate Voltage

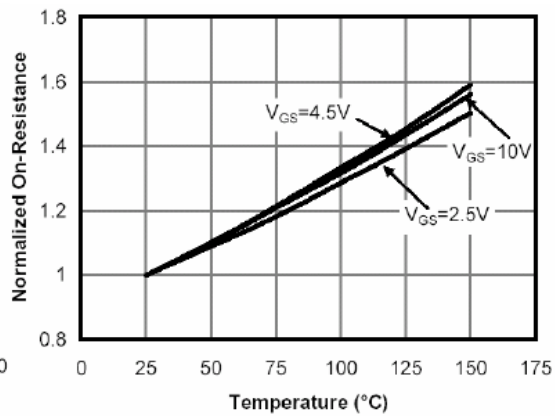


Fig 4. On-Resistance v.s. Junction Temperature

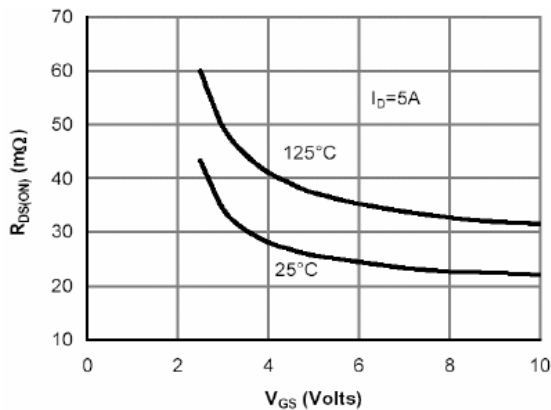


Fig 5. On-Resistance v.s. Gate-Source Voltage

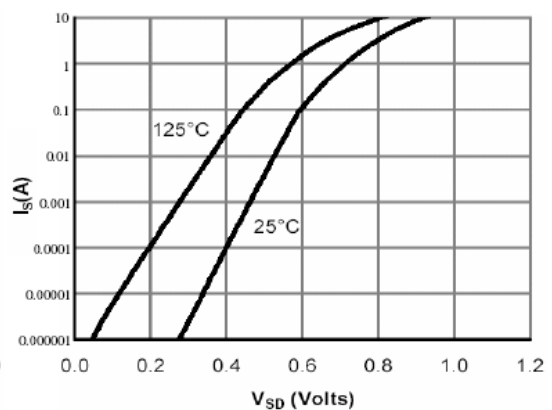
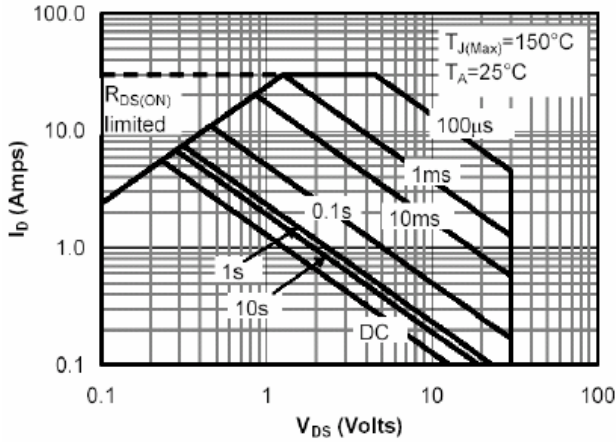
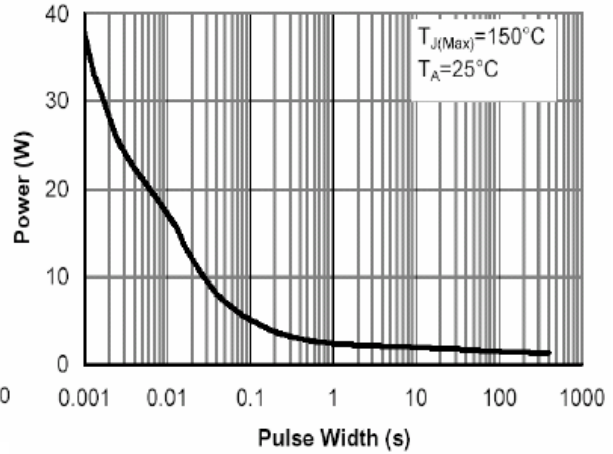
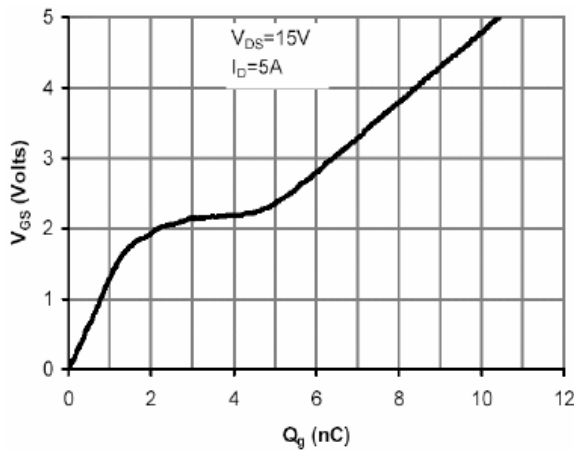
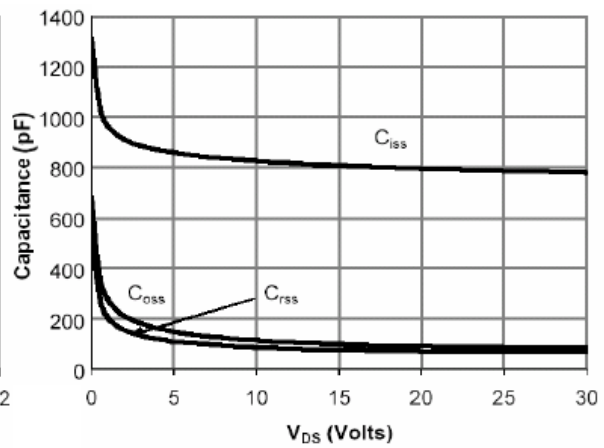
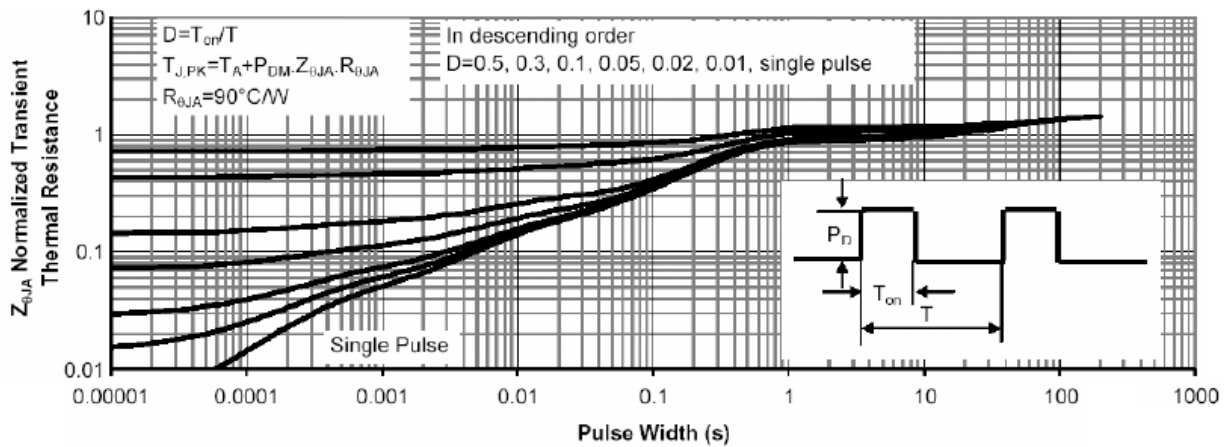
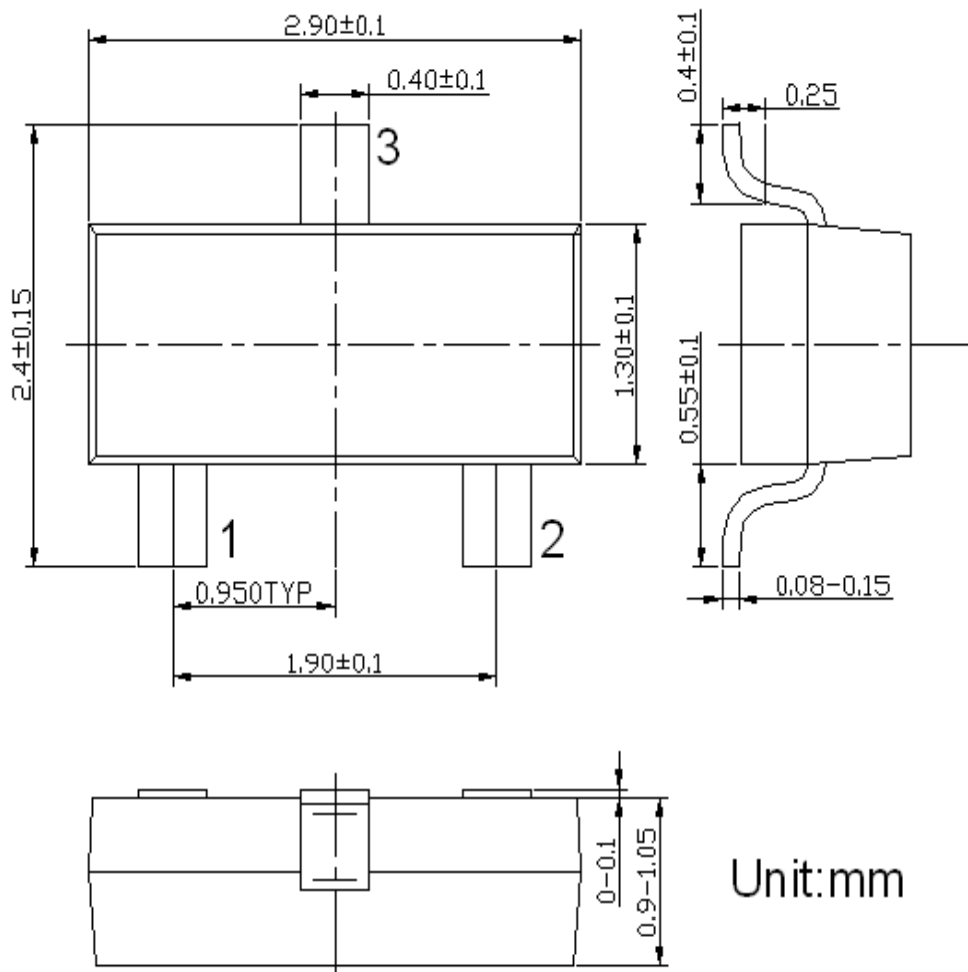


Fig 6. Body Diode Characteristics

**Typical Electrical Characteristics (N-Channel)**

**Fig 7. Maximum Safe Operating Area**

**Fig 8. Single Pulse Power Rating  
Junction-to-Ambient**

**Fig 9. Gate Charge Characteristics**

**Fig 10. Typical Capacitance Characteristics**

**Fig 11. Normalized Maximum Transient Thermal Impedance**

**Ordering Information**

Part number	Marking	package	Quantity per reel
A03400	3400	SOT23	3000

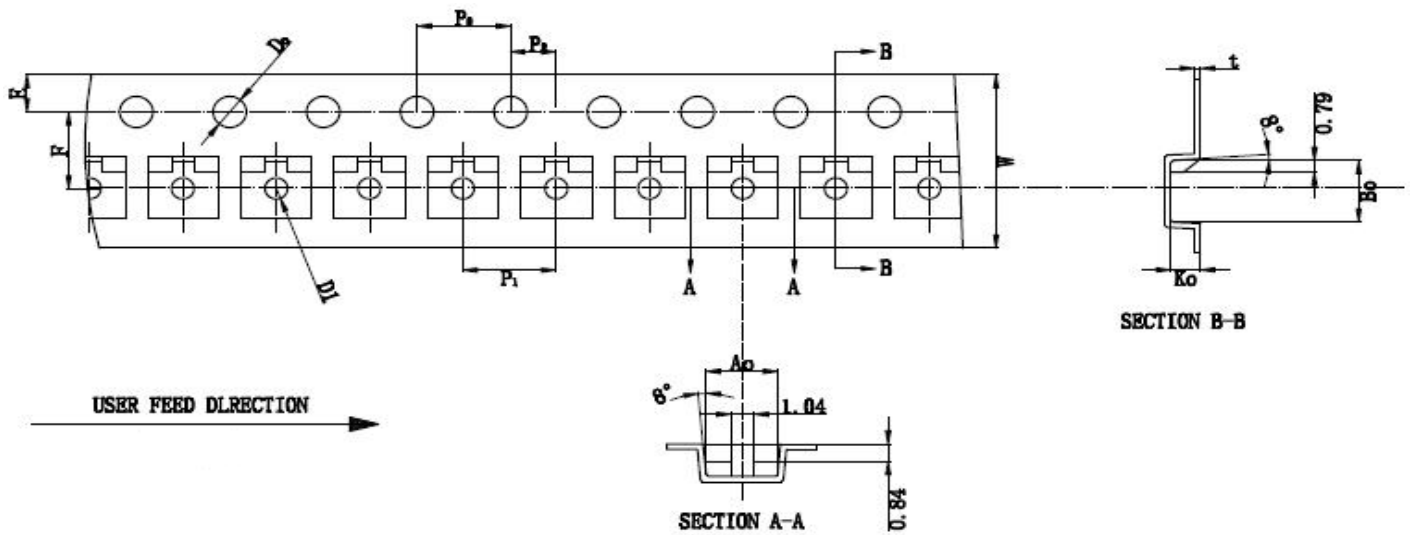
**Package Information**
**( SOT23 )**


Unit:mm

### Carrier Dimensions

PKG TYPE	W	P	E	F	D	D1	Po	Po10	P2
SOT23	8.00	4.00	1.75	3.50	1.50	1.00	4.00	40.00	2.00
Tolerance	+0.3/-0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.2	±0.05

A0	B0	K0	T
3.15	2.77	1.22	0.20
±0.1	±0.1	±0.1	±0.02



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